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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	HCS12
Core Size	16-Bit
Speed	25MHz
Connectivity	CANbus, I²C, SCI, SPI
Peripherals	PWM, WDT
Number of I/O	59
Program Memory Size	256KB (256K x 8)
Program Memory Type	FLASH
EEPROM Size	4K x 8
RAM Size	12K x 8
Voltage - Supply (Vcc/Vdd)	2.35V ~ 5.25V
Data Converters	A/D 8x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	80-QFP
Supplier Device Package	80-QFP (14x14)
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/mc9s12dt256mfue

Section 3 System Clock Description

Section 4 Modes of Operation

Section 5 Resets and Interrupts

Section 6 HCS12 Core Block Description

Section 1 IntroductionMC9S12DT256

1.1 Overview

The MC9S12DT256 microcontroller unit (MCU) is a 16-bit device composed of standard on-chip peripherals including a 16-bit central processing unit (HCS12 CPU), 256K bytes of Flash EEPROM, 12K bytes of RAM, 4K bytes of EEPROM, two asynchronous serial communications interfaces (SCI), three serial peripheral interfaces (SPI), an 8-channel IC/OC enhanced capture timer, two 8-channel, 10-bit analog-to-digital converters (ADC), an 8-channel pulse-width modulator (PWM), a digital Byte Data Link Controller (BDLC), 29 discrete digital I/O channels (Port A, Port B, Port K and Port E), 20 discrete digital I/O lines with interrupt and wakeup capability, three CAN 2.0 A, B software compatible modules (MSCAN12), and an Inter-IC Bus. The MC9S12DT256 has full 16-bit data paths throughout. However, the external bus can operate in an 8-bit narrow mode so single 8-bit wide memory can be interfaced for lower cost systems. The inclusion of a PLL circuit allows power consumption and performance to be adjusted to suit operational requirements.

1.2 Features

- HCS12 Core
  - 16-bit HCS12 CPU
    i. Upward compatible with M68HC11 instruction set
    ii. Interrupt stacking and programmer’s model identical to M68HC11
    iii. Instruction queue
    iv. Enhanced indexed addressing
  - MEBI (Multiplexed External Bus Interface)
  - MMC (Module Mapping Control)
  - INT (Interrupt control)
  - BKP (Breakpoints)
  - BDM (Background Debug Mode)
- CRG
  - Low current Colpitts or Pierce oscillator
  - PLL
  - COP watchdog
  - Real time interrupt
  - Clock Monitor
- 8-bit and 4-bit ports with interrupt functionality
  - Digital filtering

Table 1-1 Device Memory Map

Address	Module	Size (Bytes)
$1000 - $3FFF	RAM array	12288
$4000 - $7FFF	Fixed Flash EEPROM array incl. 0.5K, 1K, 2K or 4K Protected Sector at start	16384
$8000 - $BFFF	Flash EEPROM Page Window	16384
$C000 - $FFFF	Fixed Flash EEPROM array incl. 0.5K, 1K, 2K or 4K Protected Sector at end and 256 bytes of Vector Space at $FF80 - $FFFF	16384

$00A0 - $00C7 PWM (Pulse Width Modulator 8 Bit 8 Channel)

Address	Name		Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
$00B1	PWMCNT5	Read:	Bit 7	6	5	4	3	2	1	Bit 0
		Write:	0	0	0	0	0	0	0	0
$00B2	PWMCNT6	Read:	Bit 7	6	5	4	3	2	1	Bit 0
		Write:	0	0	0	0	0	0	0	0
$00B3	PWMCNT7	Read:	Bit 7	6	5	4	3	2	1	Bit 0
		Write:	0	0	0	0	0	0	0	0
$00B4	PWMPER0	Read: Write:	Bit 7	6	5	4	3	2	1	Bit 0
$00B5	PWMPER1	Read: Write:	Bit 7	6	5	4	3	2	1	Bit 0
$00B6	PWMPER2	Read: Write:	Bit 7	6	5	4	3	2	1	Bit 0
$00B7	PWMPER3	Read: Write:	Bit 7	6	5	4	3	2	1	Bit 0
$00B8	PWMPER4	Read: Write:	Bit 7	6	5	4	3	2	1	Bit 0
$00B9	PWMPER5	Read: Write:	Bit 7	6	5	4	3	2	1	Bit 0
$00BA	PWMPER6	Read: Write:	Bit 7	6	5	4	3	2	1	Bit 0
$00BB	PWMPER7	Read: Write:	Bit 7	6	5	4	3	2	1	Bit 0
$00BC	PWMDTY0	Read: Write:	Bit 7	6	5	4	3	2	1	Bit 0
$00BD	PWMDTY1	Read: Write:	Bit 7	6	5	4	3	2	1	Bit 0
$00BE	PWMDTY2	Read: Write:	Bit 7	6	5	4	3	2	1	Bit 0
$00BF	PWMDTY3	Read: Write:	Bit 7	6	5	4	3	2	1	Bit 0
$00C0	PWMDTY4	Read: Write:	Bit 7	6	5	4	3	2	1	Bit 0
$00C1	PWMDTY5	Read: Write:	Bit 7	6	5	4	3	2	1	Bit 0
$00C2	PWMDTY6	Read: Write:	Bit 7	6	5	4	3	2	1	Bit 0
$00C3	PWMDTY7	Read: Write:	Bit 7	6	5	4	3	2	1	Bit 0
$00C4	PWMSDN	Read:	PWMIF	PWMIE	PWMRSTRT	PWMLVL	0	PWM7IN	PWM7INL	PWM7ENA
		Write:								
$00C5	Reserved	Read:	0	0	0	0	0	0	0	0
		Write:								
$00C6	Reserved	Read:	0	0	0	0	0	0	0	0
		Write:								
$00C7	Reserved	Read:	0	0	0	0	0	0	0	0
		Write:								

$00F0 - $00F7 SPI1 (Serial Peripheral Interface)

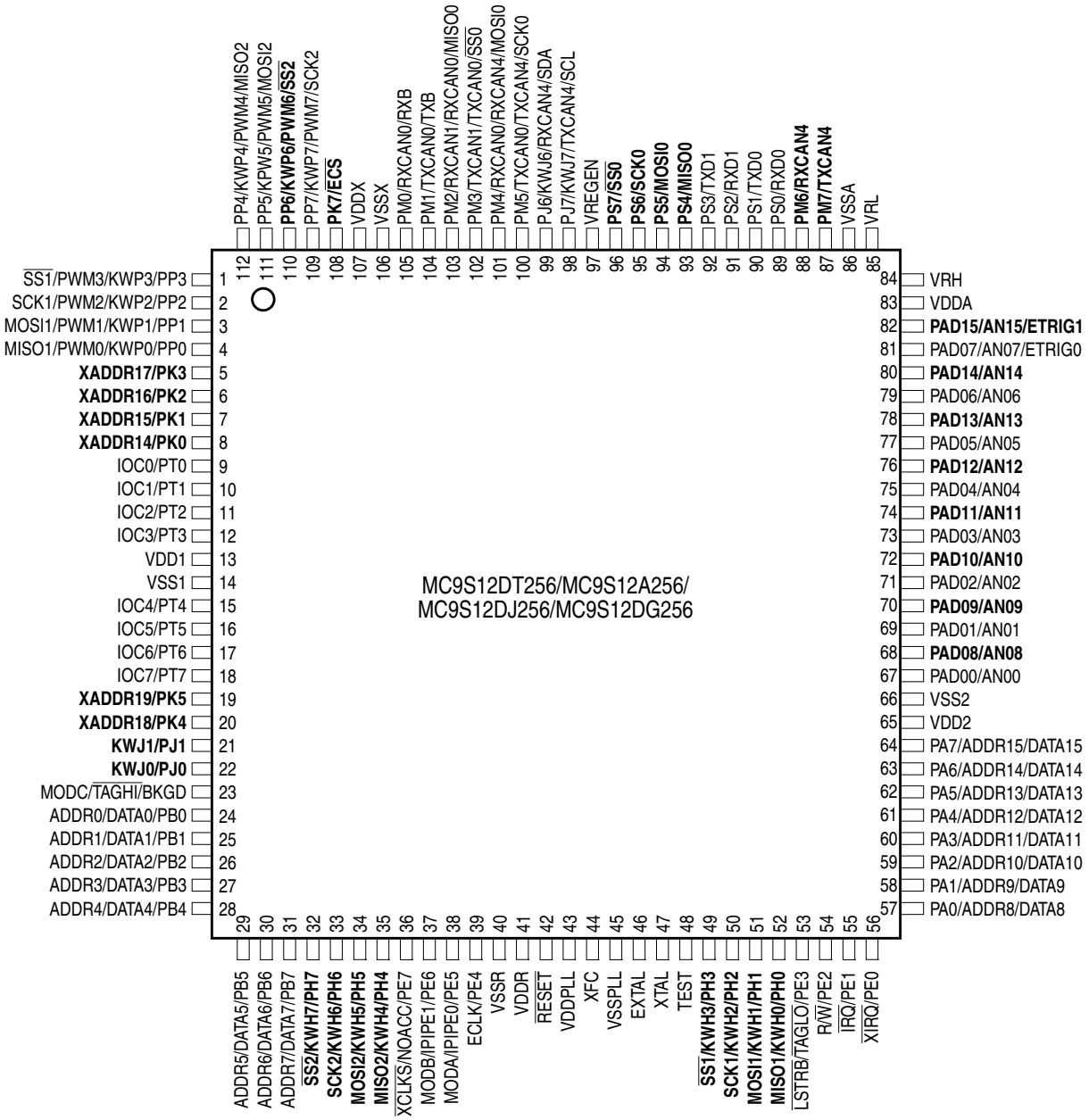
Address	Name		Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
$00F0	SPI1CR1	Read:	SPIE	SPE	SPTIE	MSTR	CPOL	CPHA	SSOE	LSBFE
		Write:								
$00F1	SPI1CR2	Read:	0	0	0	MODFEN	BIDIROE	0	SPISWAI	SPC0
		Write:								
$00F2	SPI1BR	Read:	0	SPPR2	SPPR1	SPPR0	0	SPR2	SPR1	SPR0
		Write:								
$00F3	SPI1SR	Read:	SPIF	0	SPTEF	MODF	0	0	0	0
		Write:								
$00F4	Reserved	Read:	0	0	0	0	0	0	0	0
		Write:								
$00F5	SPI1DR	Read:	Bit7	6	5	4	3	2	1	Bit0
		Write:								
$00F6	Reserved	Read:	0	0	0	0	0	0	0	0
		Write:								
$00F7	Reserved	Read:	0	0	0	0	0	0	0	0
		Write:								

$00F8 - $00FF SPI2 (Serial Peripheral Interface)

Address	Name		Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
$00F8	SPI2CR1	Read:	SPIE	SPE	SPTIE	MSTR	CPOL	CPHA	SSOE	LSBFE
		Write:								
$00F9	SPI2CR2	Read:	0	0	0	MODFEN	BIDIROE	0	SPISWAI	SPC0
		Write:								
$00FA	SPI2BR	Read:	0	SPPR2	SPPR1	SPPR0	0	SPR2	SPR1	SPR0
		Write:								
$00FB	SPI2SR	Read:	SPIF	0	SPTEF	MODF	0	0	0	0
		Write:								
$00FC	Reserved	Read:	0	0	0	0	0	0	0	0
		Write:								
$00FD	SPI2DR	Read:	Bit7	6	5	4	3	2	1	Bit0
		Write:								
$00FE	Reserved	Read:	0	0	0	0	0	0	0	0
		Write:								
$00FF	Reserved	Read:	0	0	0	0	0	0	0	0
		Write:								

$0100 - $010F Flash Control Register (fts256k)

Address	Name		Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
$0100	FCLKDIV	Read:	FDIVLD	PRDIV8	FDIV5	FDIV4	FDIV3	FDIV2	FDIV1	FDIV0
		Write:								
$0101	FSEC	Read:	KEYEN1	KEYEN0	NV5	NV4	NV3	NV2	SEC1	SEC0
		Write:								
$0102	FTSTMOD	Read:	0	0	0	WRALL	0	0	0	0
		Write:								
$0103	FCNFG	Read:	CBEIE	CCIE	KEYACC	0	0	0	BKSEL1	BKSEL0
		Write:								



Signals shown in **Bold** are not available on the 80 Pin Package

Figure 2-1 Pin Assignments in 112-pin LQFP

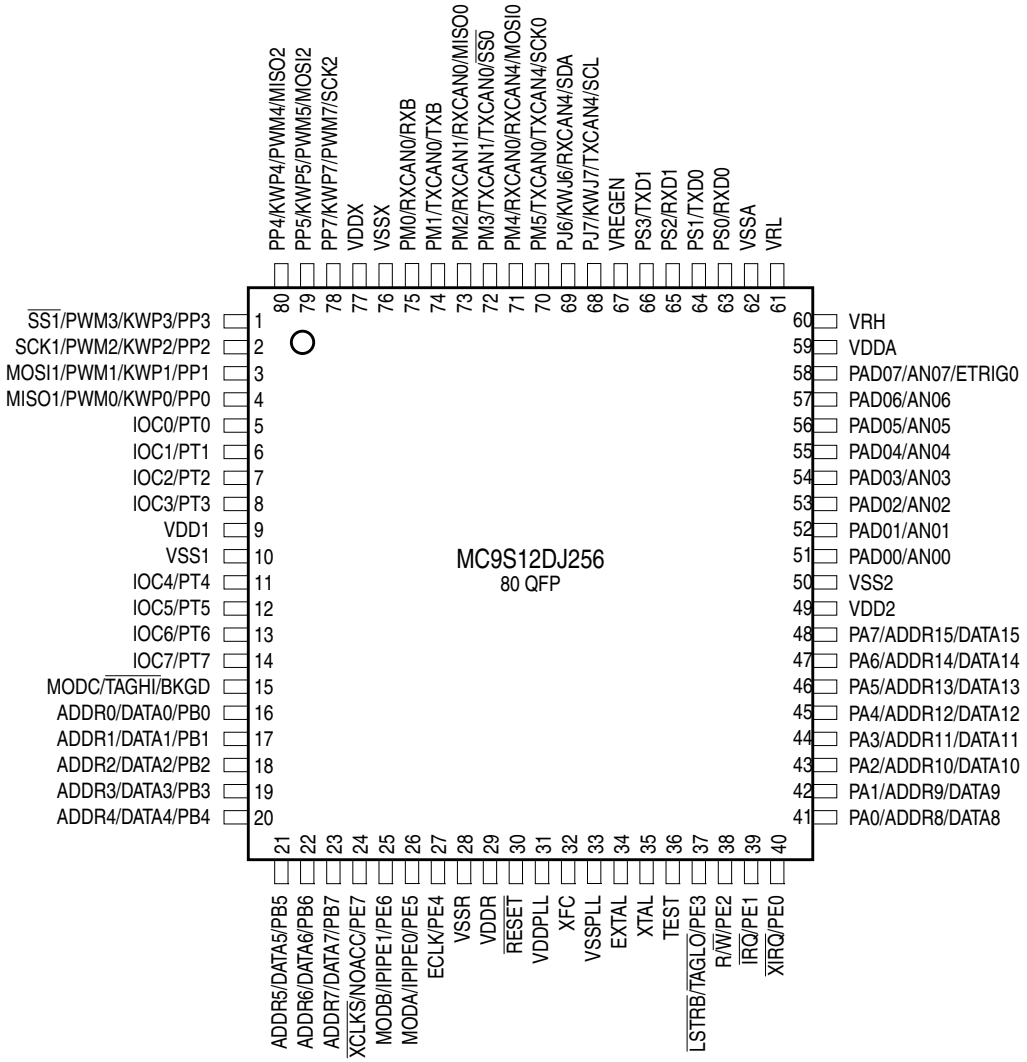


Figure 2-2 Pin Assignments in 80-pin QFP for MC9S12DJ256

2.2 Signal Properties Summary

Table 2-1summarizes the pin functionality. Signals shown in **bold** are not available in the 80 pin package.

Table 2-1 Signal Properties

Pin Name Funct. 1	Pin Name Funct. 2	Pin Name Funct. 3	Pin Name Funct. 4	Pin Name Funct. 5	Power Supply	Internal Pull Resistor		Description
						CTRL	Reset State	
EXTAL	—	—	—	—	VDDPLL	NA	NA	Oscillator Pins
XTAL	—	—	—	—	VDDPLL	NA	NA	
$\overline{\text{RESET}}$	—	—	—	—	VDDR	None	None	External Reset
TEST	—	—	—	—	N.A.	NA	NA	Test Input
VREGEN	—	—	—	—	VDDX	NA	NA	Voltage Regulator Enable Input
XFC	—	—	—	—	VDDPLL	NA	NA	PLL Loop Filter
BKGD	$\overline{\text{TAGHI}}$	MODC	—	—	VDDR	Always Up	Up	Background Debug, Tag High, Mode Input
PAD[15]	**AN1[7]**	**ETRIG1**	**—**	**—**	**VDDA**	**None**	**None**	**Port AD Input, Analog Input AN7 of ATD1, External Trigger Input of ATD1**
PAD[14:8]	**AN1[6:0]**	**—**	**—**	**—**	**VDDA**	**None**	**None**	**Port AD Inputs, Analog Inputs AN[6:0] of ATD1**
PAD[7]	AN0[7]	ETRIG0	—	—	VDDA	None	None	Port AD Input, Analog Input AN7 of ATD0, External Trigger Input of ATD0
PAD[6:0]	AN0[6:0]	—	—	—	VDDA	None	None	Port AD Inputs, Analog Inputs AN[6:0] of ATD0
PA[7:0]	ADDR[15:8]/ DATA[15:8]	—	—	—	VDDR	PUCR	Disabled	Port A I/O, Multiplexed Address/Data
PB[7:0]	ADDR[7:0]/ DATA[7:0]	—	—	—	VDDR	PUCR	Disabled	Port B I/O, Multiplexed Address/Data
PE7	NOACC	$\overline{\text{XCLKS}}$	—	—	VDDR	PUCR	Up	Port E I/O, Access, Clock Select
PE6	IPIPE1	MODB	—	—	VDDR	While $\overline{\text{RESET}}$ pin is low: Down		Port E I/O, Pipe Status, Mode Input
PE5	IPIPE0	MODA	—	—	VDDR	While RESET pin is low: Down		Port E I/O, Pipe Status, Mode Input
PE4	ECLK	—	—	—	VDDR	PUCR	Up	Port E I/O, Bus Clock Output
PE3	$\overline{\text{LSTRB}}$	$\overline{\text{TAGLO}}$	—	—	VDDR	PUCR	Up	Port E I/O, Byte Strobe, Tag Low
PE2	R/$\overline{\text{W}}$	—	—	—	VDDR	PUCR	Up	Port E I/O, R/$\overline{\text{W}}$ in expanded modes
PE1	$\overline{\text{IRQ}}$	—	—	—	VDDR	PUCR	Up	Port E Input, Maskable Interrupt
PE0	$\overline{\text{XIRQ}}$	—	—	—	VDDR	PUCR	Up	Port E Input, Non Maskable Interrupt
PH7	**KWH7**	**$\overline{\text{SS2}}$**	**—**	**—**	**VDDR**	**PERH/ PPSH**	**Disabled**	**Port H I/O, Interrupt, $\overline{\text{SS}}$ of SPI2**
PH6	**KWH6**	**SCK2**	**—**	**—**	**VDDR**	**PERH/ PPSH**	**Disabled**	**Port H I/O, Interrupt, SCK of SPI2**
PH5	**KWH5**	**MOSI2**	**—**	**—**	**VDDR**	**PERH/ PPSH**	**Disabled**	**Port H I/O, Interrupt, MOSI of SPI2**

Pin Name Funct. 1	Pin Name Funct. 2	Pin Name Funct. 3	Pin Name Funct. 4	Pin Name Funct. 5	Power Supply	Internal Pull Resistor		Description
						CTRL	Reset State	
PH4	**KWH4**	**MISO2**	**—**	**—**	**VDDR**	**PERH/ PPSH**	**Disabled**	**Port H I/O, Interrupt, MISO of SPI2**
PH3	**KWH3**	**$\overline{SS1}$**	**—**	**—**	**VDDR**	**PERH/ PPSH**	**Disabled**	**Port H I/O, Interrupt, $\overline{SS}$ of SPI1**
PH2	**KWH2**	**SCK1**	**—**	**—**	**VDDR**	**PERH/ PPSH**	**Disabled**	**Port H I/O, Interrupt, SCK of SPI1**
PH1	**KWH1**	**MOSI1**	**—**	**—**	**VDDR**	**PERH/ PPSH**	**Disabled**	**Port H I/O, Interrupt, MOSI of SPI1**
PH0	**KWH0**	**MISO1**	**—**	**—**	**VDDR**	**PERH/ PPSH**	**Disabled**	**Port H I/O, Interrupt, MISO of SPI1**
PJ7	KWJ7	TXCAN4	SCL	TXCAN0	VDDX	PERJ/ PPSJ	Up	Port J I/O, Interrupt, TX of CAN4, SCL of IIC, TX of CAN0
PJ6	KWJ6	RXCAN4	SDA	RXCAN0	VDDX	PERJ/ PPSJ	Up	Port J I/O, Interrupt, RX of CAN4, SDA of IIC, RX of CAN0
PJ[1:0]	**KWJ[1:0]**	**—**	**—**	**—**	**VDDX**	**PERJ/ PSJ**	**Up**	**Port J I/O, Interrupts**
PK7	**ECS**	**ROMONE**	**—**	**—**	**VDDX**	**PUCR**	**Up**	**Port K I/O, Emulation Chip Select, ROM On Enable**
PK[5:0]	**XADDR [19:14]**	**—**	**—**	**—**	**VDDX**	**PUCR**	**Up**	**Port K I/O, Extended Addresses**
PM7	**TXCAN4**	**—**	**—**	**—**	**VDDX**	**PERM/ PPSM**	**Disabled**	**Port M I/O, TX of CAN4**
PM6	**RXCAN4**	**—**	**—**	**—**	**VDDX**	**PERM/ PPSM**	**Disabled**	**Port M I/O RX of CAN4**
PM5	TXCAN0	TXCAN4	SCK0	—	VDDX	PERM/ PPSM	Disabled	Port M I/OCAN0, CAN4, SCK of SPI0
PM4	RXCAN0	RXCAN4	MOSI0	—	VDDX	PERM/ PPSM	Disabled	Port M I/O, CAN0, CAN4, MOSI of SPI0
PM3	TXCAN1	TXCAN0	—	$\overline{SS0}$	VDDX	PERM/ PPSM	Disabled	Port M I/O, TX of CAN1, CAN0, $\overline{SS}$ of SPI0
PM2	RXCAN1	RXCAN0	—	MISO0	VDDX	PERM/ PPSM	Disabled	Port M I/O, RX of CAN1, CAN0, MISO of SPI0
PM1	TXCAN0	TXB	—	—	VDDX	PERM/ PPSM	Disabled	Port M I/O, TX of CAN0, TX of BDLC
PM0	RXCAN0	RXB	—	—	VDDX	PERM/ PPSM	Disabled	Port M I/O, RX of CAN0, RX of BDLC
PP7	KWP7	PWM7	SCK2	—	VDDX	PERP/ PPSP	Disabled	Port P I/O, Interrupt, Channel 7 of PWM, SCK of SPI2
PP6	**KWP6**	**PWM6**	**$\overline{SS2}$**	**—**	**VDDX**	**PERP/ PPSP**	**Disabled**	**Port P I/O, Interrupt, Channel 6 of PWM, $\overline{SS}$ of SPI2**
PP5	KWP5	PWM5	MOSI2	—	VDDX	PERP/ PPSP	Disabled	Port P I/O, Interrupt, Channel 5 of PWM, MOSI of SPI2

2.3.3 TEST — Test Pin

This input only pin is reserved for test.

NOTE: *The TEST pin must be tied to VSS in all applications.*

2.3.4 VREGEN — Voltage Regulator Enable Pin

This input only pin enables or disables the on-chip voltage regulator.

2.3.5 XFC — PLL Loop Filter Pin

PLL loop filter. Please ask your Motorola representative for the interactive application note to compute PLL loop filter elements. Any current leakage on this pin must be avoided.

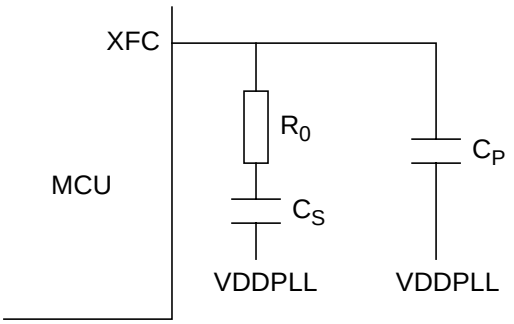


Figure 2-3 PLL Loop Filter Connections

2.3.6 BKGD / $\overline{\text{TAGHI}}$ / MODC — Background Debug, Tag High, and Mode Pin

The BKGD/$\overline{\text{TAGHI}}$/MODC pin is used as a pseudo-open-drain pin for the background debug communication. In MCU expanded modes of operation when instruction tagging is on, an input low on this pin during the falling edge of E-clock tags the high half of the instruction word being read into the instruction queue. It is used as a MCU operating mode select pin during reset. The state of this pin is latched to the MODC bit at the rising edge of $\overline{\text{RESET}}$. This pin has a permanently enabled pull-up device.

2.3.7 PAD15 / AN15 / ETRIG1 — Port AD Input Pin of ATD1

PAD15 is a general purpose input pin and analog input AN7 of the analog to digital converter ATD1. It can act as an external trigger input for the ATD1.

2.3.8 PAD[14:08] / AN[14:08] — Port AD Input Pins of ATD1

PAD14 - PAD08 are general purpose input pins and analog inputs AN[6:0] of the analog to digital converter ATD1.

Component	Purpose	Type	Value
C1	VDD1 filter cap	ceramic X7R	100 .. 220nF
C2	VDD2 filter cap	ceramic X7R	100 .. 220nF
C3	VDDA filter cap	ceramic X7R	100nF
C4	VDDR filter cap	X7R/tantalum	>=100nF
C5	VDDPLL filter cap	ceramic X7R	100nF
C6	VDDX filter cap	X7R/tantalum	>=100nF
C7	OSC load cap		
C8	OSC load cap		
C9 / C_S	PLL loop filter cap	See PLL specification chapter	
C10 / C_P	PLL loop filter cap		
C11 / C_{DC}	DC cutoff cap	Colpitts mode only, if recommended by quartz manufacturer	
R1 / R	PLL loop filter res	See PLL Specification chapter	
R2 / R_B		Pierce mode only	
R3 / R_S			
Q1	Quartz		

The PCB must be carefully laid out to ensure proper operation of the voltage regulator as well as of the MCU itself. The following rules must be observed:

- Every supply pair must be decoupled by a ceramic capacitor connected as near as possible to the corresponding pins (C1 – C6).
- Central point of the ground star should be the VSSR pin.
- Use low ohmic low inductance connections between VSS1, VSS2 and VSSR.
- VSSPLL must be directly connected to VSSR.
- Keep traces of VSSPLL, EXTAL and XTAL as short as possible and occupied board area for C7, C8, C11 and Q1 as small as possible.
- Do not place other signals or supplies underneath area occupied by C7, C8, C10 and Q1 and the connection area to the MCU.
- Central power input should be fed in at the VDDA/VSSA pins.

Figure 20-1 Recommended PCB Layout for 112LQFP Colpitts Oscillator

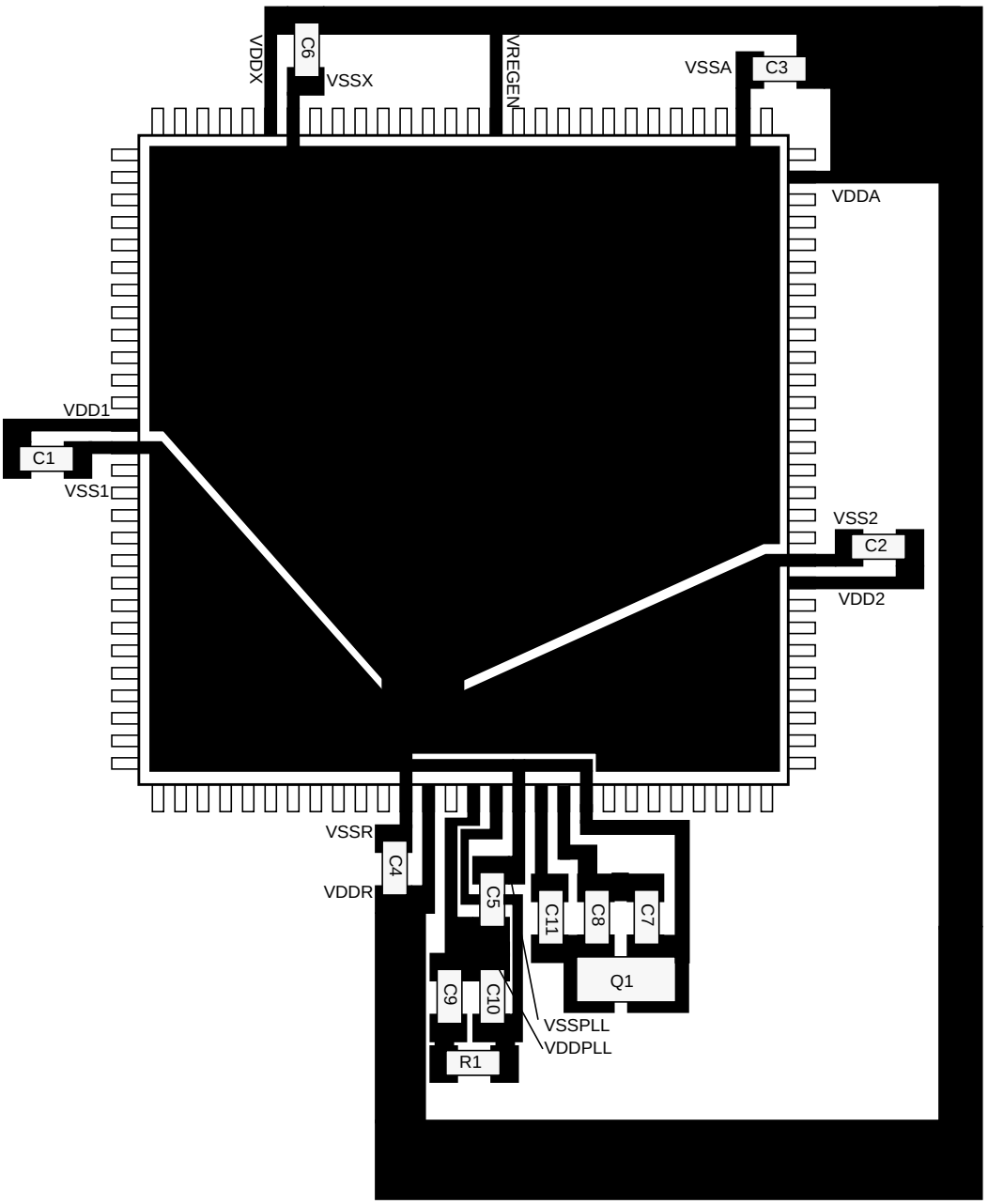
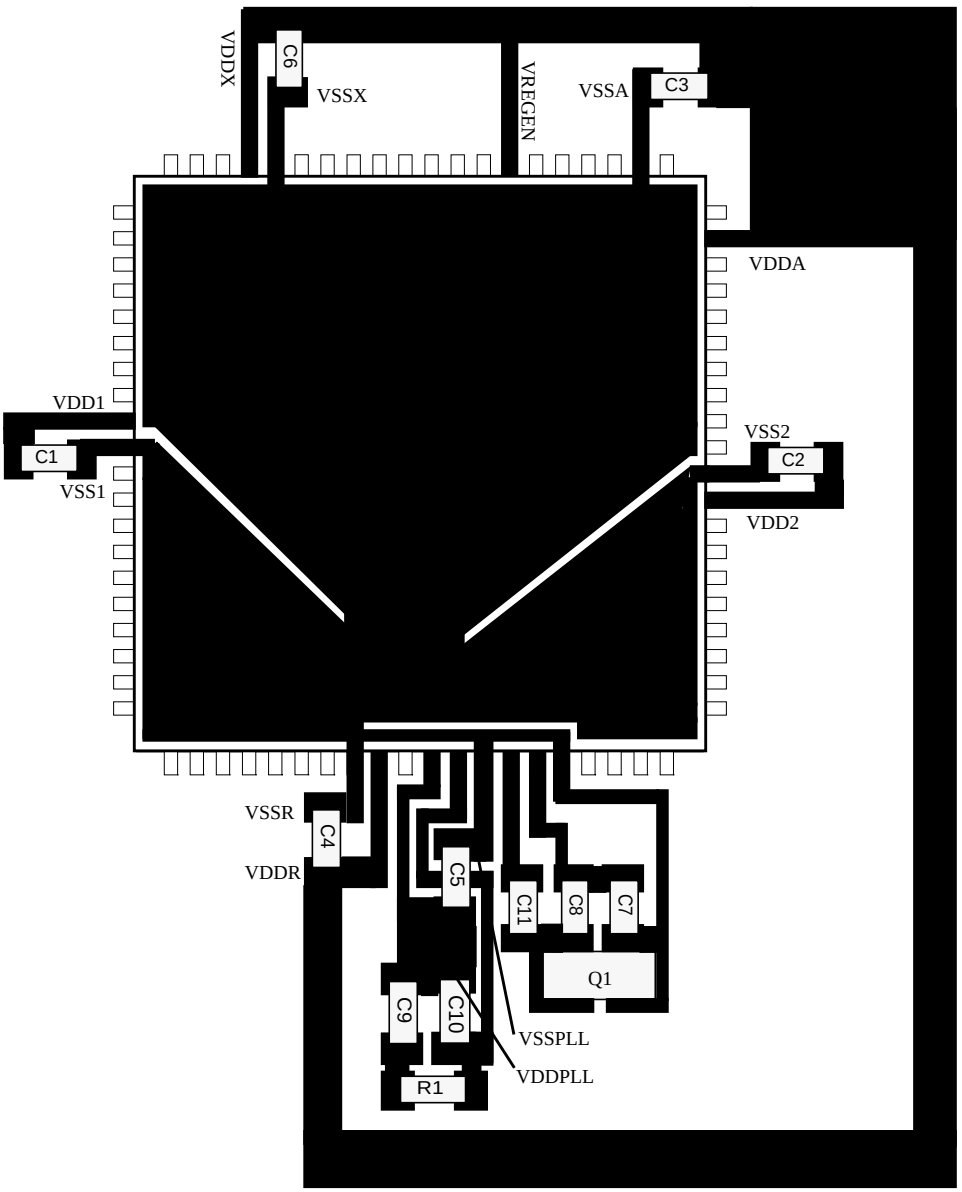


Figure 20-2 Recommended PCB Layout for 80QFP Colpitts Oscillator



A.3.2 NVM Reliability

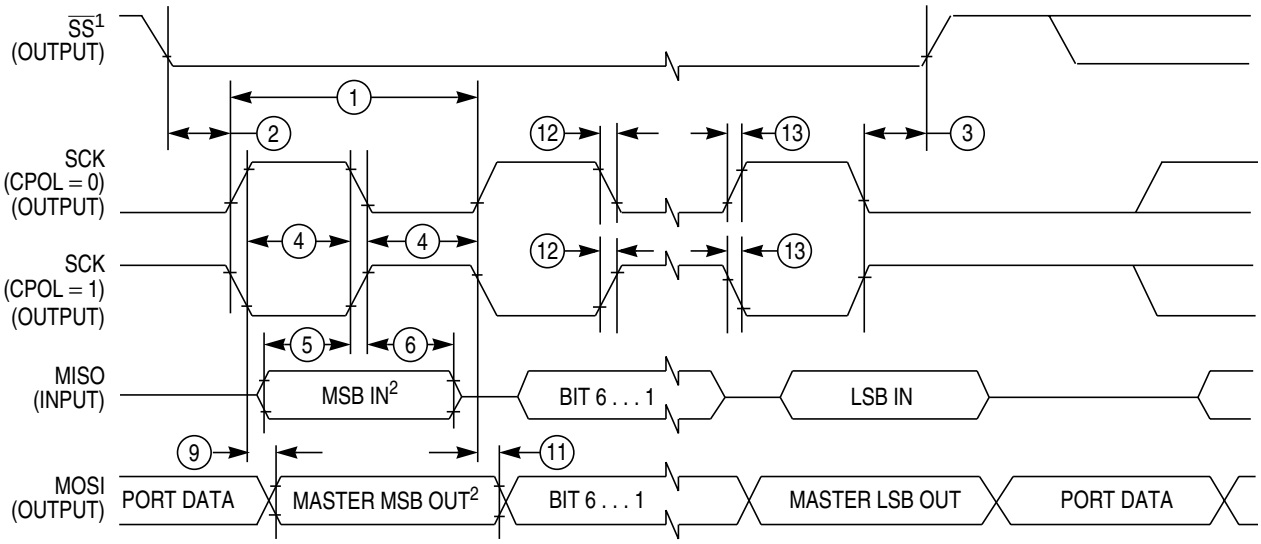
The reliability of the NVM blocks is guaranteed by stress test during qualification, constant process monitors and burn-in to screen early life failures.The program/erase cycle count on the sector is incremented every time a sector or mass erase event is executed

Table A-12 NVM Reliability Characteristics[1]

Conditions are shown in **Table A-4** unless otherwise noted							
Num	**C**	**Rating**	**Symbol**	**Min**	**Typ**	**Max**	**Unit**
Flash Reliability Characteristics							
1	C	Data retention after 10,000 program/erase cycles at an average junction temperature of $T_{Javg} \leq 85°C$	t_{FLRET}	15	100[2]	—	Years
2	C	Data retention with <100 program/erase cycles at an average junction temperature $T_{Javg} \leq 85°C$		20	100[2]	—	
3	C	Number of program/erase cycles ($-40°C \leq T_J \leq 0°C$)	n_{FL}	10,000	—	—	Cycles
4	C	Number of program/erase cycles ($0°C \leq T_J \leq 140°C$)		10,000	100,000[3]	—	
EEPROM Reliability Characteristics							
5	C	Data retention after up to 100,000 program/erase cycles at an average junction temperature of $T_{Javg} \leq 85°C$	t_{EEPRET}	15	100[2]	—	Years
6	C	Data retention with <100 program/erase cycles at an average junction temperature $T_{Javg} \leq 85°C$		20	100[2]	—	
7	C	Number of program/erase cycles ($-40°C \leq T_J \leq 0°C$)	n_{EEP}	10,000	—	—	Cycles
8	C	Number of program/erase cycles ($0°C < T_J \leq 140°C$)		100,000	300,000[3]	—	

NOTES:

1. T_{Javg} will not exeed 85°C considering a typical temperature profile over the lifetime of a consumer, industrial or automotive application.
2. Typical data retention values are based on intrinsic capability of the technology measured at high temperature and de-rated to 25°C using the Arrhenius equation. For additional information on how Freescale defines Typical Data Retention, please refer to Engineering Bulletin EB618.
3. Spec table quotes typical endurance evaluated at 25°C for this product family, typical endurance at various temperature can be estimated using the graph below. For additional information on how Freescale defines Typical Endurance, please refer to Engineering Bulletin EB619.



1.If configured as output

2. LSBF = 0. For LSBF = 1, bit order is LSB, bit 1, ..., bit 6, MSB.

Figure A-7 SPI Master Timing (CPHA=1)

In **Table A-19** the timing characteristics for master mode are listed.

Table A-19 SPI Master Mode Timing Characteristics

Num	Characteristic	Symbol	Min	Typ	Max	Unit
1	SCK Frequency	f_{sck}	1/2048	—	1/2	f_{bus}
1	SCK Period	t_{sck}	2	—	2048	t_{bus}
2	Enable Lead Time	t_{lead}	—	1/2	—	t_{sck}
3	Enable Lag Time	t_{lag}	—	1/2	—	t_{sck}
4	Clock (SCK) High or Low Time	t_{wsck}	—	1/2	—	t_{sck}
5	Data Setup Time (Inputs)	t_{su}	8	—	—	ns
6	Data Hold Time (Inputs)	t_{hi}	8	—	—	ns
9	Data Valid after SCK Edge	t_{vsck}	—	—	30	ns
10	Data Valid after $\overline{SS}$ fall (CPHA=0)	t_{vss}	—	—	15	ns
11	Data Hold Time (Outputs)	t_{ho}	20	—	—	ns
12	Rise and Fall Time Inputs	t_{rfi}	—	—	8	ns
13	Rise and Fall Time Outputs	t_{rfo}	—	—	8	ns

A.7.2 Slave Mode

In **Figure A-8** the timing diagram for slave mode with transmission format CPHA=0 is depicted.

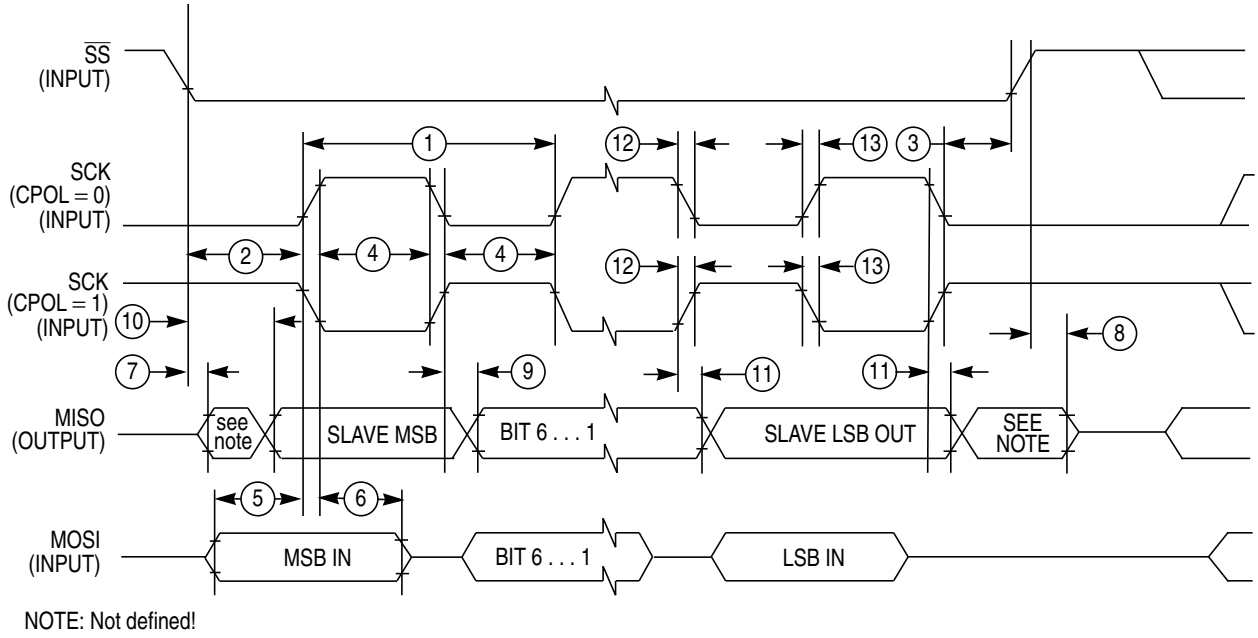


Figure A-8 SPI Slave Timing (CPHA=0)

In **Figure A-9** the timing diagram for slave mode with transmission format CPHA=1 is depicted.

Table A-21 Expanded Bus Timing Characteristics

Conditions are shown in **Table A-4** unless otherwise noted, C_{LOAD} = 50pF							
Num	**C**	**Rating**	**Symbol**	**Min**	**Typ**	**Max**	**Unit**
1	P	Frequency of operation (E-clock)	f_o	0		25.0	MHz
2	P	Cycle time	t_{cyc}	40			ns
3	D	Pulse width, E low	PW_{EL}	19			ns
4	D	Pulse width, E high[1]	PW_{EH}	19			ns
5	D	Address delay time	t_{AD}			8	ns
6	D	Address valid time to E rise (PW_{EL}–t_{AD})	t_{AV}	11			ns
7	D	Muxed address hold time	t_{MAH}	2			ns
8	D	Address hold to data valid	t_{AHDS}	7			ns
9	D	Data hold to address	t_{DHA}	2			ns
10	D	Read data setup time	t_{DSR}	13			ns
11	D	Read data hold time	t_{DHR}	0			ns
12	D	Write data delay time	t_{DDW}			7	ns
13	D	Write data hold time	t_{DHW}	2			ns
14	D	Write data setup time[1] (PW_{EH}–t_{DDW})	t_{DSW}	12			ns
15	D	Address access time[1] (t_{cyc}–t_{AD}–t_{DSR})	t_{ACCA}	19			ns
16	D	E high access time[1] (PW_{EH}–t_{DSR})	t_{ACCE}	6			ns
17	D	Non-multiplexed address delay time	t_{NAD}			6	ns
18	D	Non-muxed address valid to E rise (PW_{EL}–t_{NAD})	t_{NAV}	15			ns
19	D	Non-multiplexed address hold time	t_{NAH}	2			ns
20	D	Chip select delay time	t_{CSD}			16	ns
21	D	Chip select access time[1] (t_{cyc}–t_{CSD}–t_{DSR})	t_{ACCS}	11			ns
22	D	Chip select hold time	t_{CSH}	2			ns
23	D	Chip select negated time	t_{CSN}	8			ns
24	D	Read/write delay time	t_{RWD}			7	ns
25	D	Read/write valid time to E rise (PW_{EL}–t_{RWD})	t_{RWV}	14			ns
26	D	Read/write hold time	t_{RWH}	2			ns
27	D	Low strobe delay time	t_{LSD}			7	ns
28	D	Low strobe valid time to E rise (PW_{EL}–t_{LSD})	t_{LSV}	14			ns
29	D	Low strobe hold time	t_{LSH}	2			ns
30	D	NOACC strobe delay time	t_{NOD}			7	ns
31	D	NOACC valid time to E rise (PW_{EL}–t_{NOD})	t_{NOV}	14			ns

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